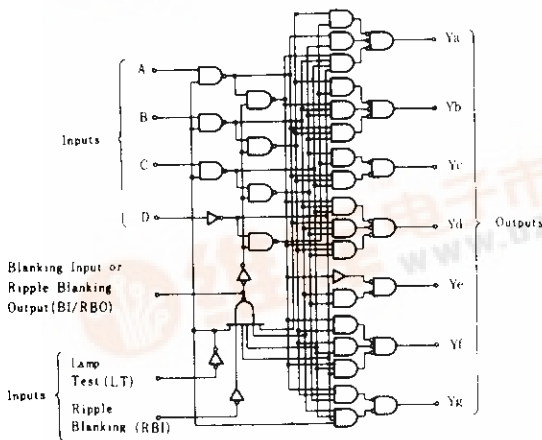


HD74LS48

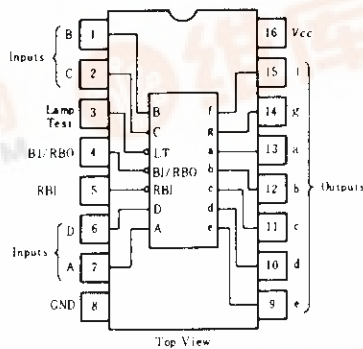
BCD-to-Seven-Segment Decoder Driver (Internal Pull-up outputs)

The HD74LS48 features active high outputs for driving lamp buffers. This circuit has full ripple blanking input/output controls and a lamp test input. Display patterns for BCD input counts above 9 are unique symbols to authenticate input conditions. This circuit incorporates automatic leading and/or trailing-edge zero-blanking control (RBI and RBO). Lamp test (LT) of these types may be performed at any time when the BI/RBO node is at a high level. It contains an overriding blanking input (BI) which can be used to control the lamp intensity by pulsing or to inhibit the outputs. Inputs and outputs are entirely compatible for use with TTL or DTL logic outputs.

BLOCK DIAGRAM



PIN ARRANGEMENT



RECOMMENDED OPERATING CONDITIONS

Item	Symbol	min	typ	max	Unit
High level output current	I_{OH} a-g	—	—	-100	μA
	BI/RBO	—	—	-50	μA
Low level output current	I_{OL} a-g	—	—	6	mA
	BI/RBO	—	—	3.2	mA

FUNCTION TABLE

Decimal or Function	Inputs								Outputs							Note
	LT	RBI	D	C	B	A	BI/RBO	a	b	c	d	e	f	g		
0	H	H	L	L	L	L	H	H	H	H	H	H	H	L		
1	H	X	L	L	L	H	H	L	H	H	L	L	L	L		
2	H	X	L	L	H	L	H	H	H	H	L	L	L	H		
3	H	X	L	L	H	H	H	H	H	H	L	L	L	H		
4	H	X	L	H	L	L	H	L	H	H	L	L	H	H		
5	H	X	L	H	L	H	H	H	L	L	H	H	H	H		
6	H	X	L	H	H	L	H	L	L	H	H	H	H	H		
7	H	X	L	H	H	H	H	H	H	H	L	L	L	L		
8	H	X	H	L	L	L	H	H	H	H	H	H	H	H		
9	H	X	H	L	L	H	H	H	H	H	L	L	H	H		
10	H	X	H	L	H	L	H	L	L	L	H	H	L	H		
11	H	X	H	L	H	H	H	L	L	L	H	H	L	H		
12	H	X	H	H	L	L	H	L	H	L	L	L	H	H		
13	H	X	H	H	L	H	H	H	L	L	L	L	H	H		
14	H	X	H	H	H	L	H	L	L	L	H	H	H	H		
15	H	X	H	H	H	H	H	L	L	L	L	L	L	L		
BI	X	X	X	X	X	X	L	L	L	L	L	L	L	L		
RBI	H	L	L	L	L	L	L	L	L	L	L	L	L	L		
LT	L	X	X	X	X	X	H	H	H	H	H	H	H	H		

- H; high level, L; low level, X; irrelevant
- Notes:
- The blanking input (BI) must be open or held at a high logic level when output functions 0 through 15 are desired.
 - When a low logic level is applied directly to the blanking input (BI), all segment outputs are low regardless of the level of any other input.
 - When ripple-blanking input (RBI) and inputs A, B, C, and D are at a low level with the lamp-test input high, all segment outputs go low and the ripple-blanking output (RBO)

- goes to a low level (response condition).
- When a blanking input/ripple blanking output (BI/RBO) is open or held high and a low is applied to the lamp-test input, all segment outputs are high.



HD74LS48

ELECTRICAL CHARACTERISTICS ($T_a = -20 \sim +75^\circ\text{C}$)

Item	Symbol	Test Conditions	min	typ*	max	Unit	
Input voltage	V_{IH}		2.0	—	—	V	
	V_{IL}		—	—	0.8	V	
Output voltage	a ~ g BI/RBO	V_{OH}	$V_{CC}=4.75\text{V}, V_{IH}=2\text{V}, V_{IL}=0.8\text{V}$	$I_{OH} = -100\mu\text{A}$ $I_{OH} = -50\mu\text{A}$	2.4	—	V
	a ~ g	V_{OL}	$V_{CC}=4.75\text{V}, V_{IH}=2\text{V}, V_{IL}=0.8\text{V}$	$I_{OL} = 2\text{mA}$	—	0.4	V
	BI/RBO			$I_{OL} = 6\text{mA}$	—	0.5	
				$I_{OL} = 1.6\text{mA}$	—	0.4	
			$I_{OL} = 3.2\text{mA}$	—	0.5		
Output current **	a ~ g	I_o	$V_{CC}=4.75\text{V}, V_o=0.85\text{V}$	-1.3	—	—	mA
Input current	except BI/RBO	I_{IH}	$V_{CC}=5.25\text{V}, V_i=2.7\text{V}$	—	—	20	μA
	BI/RBO	I_{IL}	$V_{CC}=5.25\text{V}, V_i=0.4\text{V}$	—	—	-0.4	mA
	except BI/RBO	I_i	$V_{CC}=5.25\text{V}, V_i=7\text{V}$	—	—	-1.2	
					—	—	0.1
Short-circuit output current	BI/RBO	I_{OS}	$V_{CC}=5.25\text{V}$	-0.3	—	-2	mA
Supply current ***		I_{CC}	$V_{CC}=5.25\text{V}$	—	25	38	mA
Input clamp voltage		V_{IK}	$V_{CC}=4.75\text{V}, I_{IN}=-18\text{mA}$	—	—	-1.5	V

* $V_{CC}=5\text{V}, T_a=25^\circ\text{C}$

** Input condition as for V_{OH}

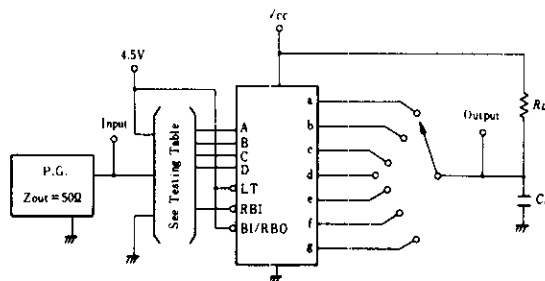
*** I_{CC} is measured with all outputs open and all inputs at 4.5V.

SWITCHING CHARACTERISTICS ($V_{CC}=5\text{V}, T_a=25^\circ\text{C}$)

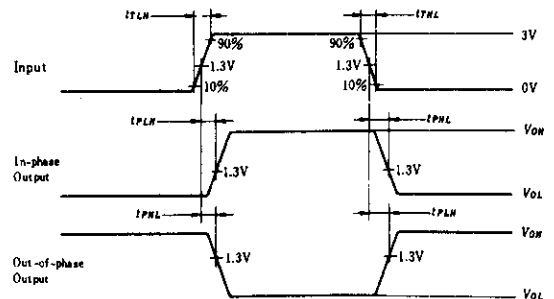
Item	Symbol	Input	Test Conditions	min	typ	max	Unit
Propagation delay time	t_{PHL}	A	$C_L=15\text{pF}, R_L=4\text{k}\Omega$	—	—	100	ns
	t_{PLH}			—	—	100	
	t_{PHL}	RBI	$C_L=15\text{pF}, R_L=6\text{k}\Omega$	—	—	100	ns
	t_{PLH}			—	—	100	

TESTING METHOD

1) Test Circuit



Waveform

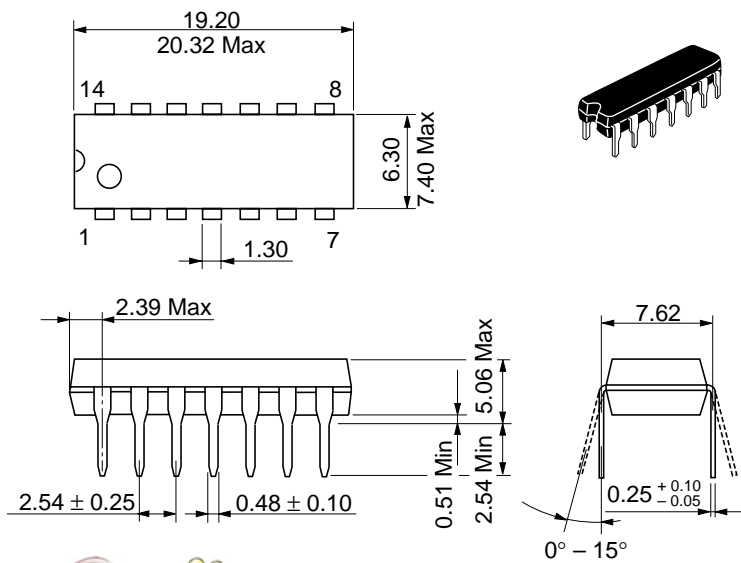


2) Testing Table

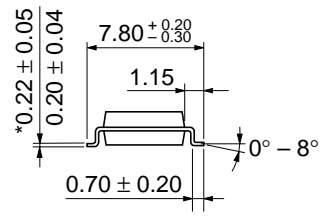
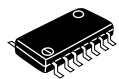
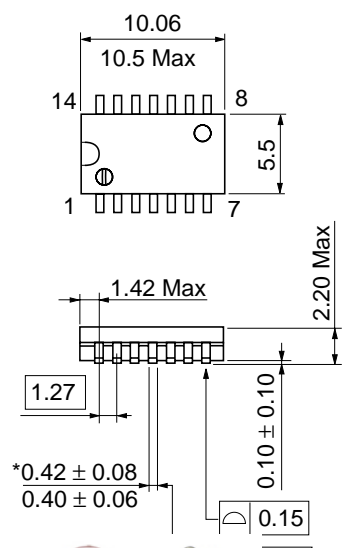
Item	Inputs					Outputs						
	RBI	D	C	B	A	a	b	c	d	e	f	g
	4.5V	GND	GND	GND	IN	OUT	—	—	OUT	OUT	OUT	—
t_{PLH}	4.5V	GND	GND	4.5V	IN	—	—	OUT	—	OUT	—	—
t_{PHL}	4.5V	GND	4.5V	4.5V	IN	OUT	OUT	—	OUT	OUT	OUT	OUT
	IN	GND	GND	GND	GND	OUT	OUT	OUT	OUT	OUT	OUT	—



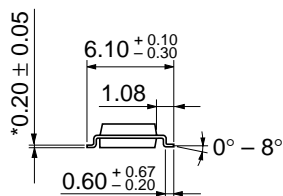
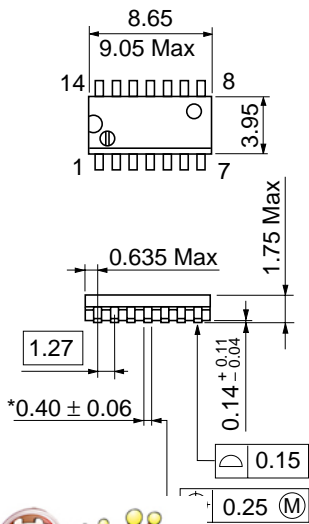
Unit: mm



Unit: mm



Unit: mm



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Hitachi, Ltd.

Semiconductor & Integrated Circuits.
Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan
Tel: Tokyo (03) 3270-2111 Fax: (03) 3270-5109

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For further information write to:

Hitachi Semiconductor
(America) Inc.
179 East Tasman Drive,
San Jose, CA 95134
Tel: <1> (408) 433-1990
Fax: <1> (408) 433-0223

Hitachi Europe GmbH
Electronic components Group
Domacher StraÙe 3
D-85622 Feldkirchen, Munich
Germany
Tel: <49> (89) 9 9180-0
Fax: <49> (89) 9 29 30 00

Hitachi Europe Ltd.
Electronic Components Group.
Whitebrook Park
Lower Cookham Road
Maidenhead
Berkshire SL6 8YA, United Kingdom
Tel: <44> (1628) 585000
Fax: <44> (1628) 778322

Hitachi Asia Pte. Ltd.
16 Collyer Quay #20-00
Hitachi Tower
Singapore 049318
Tel: 535-2100
Fax: 535-1533

Hitachi Asia Ltd.
Taipei Branch Office
3F, Hung Kuo Building, No.167,
Tun-Hwa North Road, Taipei (105)
Tel: <886> (2) 2718-3666
Fax: <886> (2) 2718-8180

Hitachi Asia (Hong Kong) Ltd.
Group III (Electronic Components)
7/F., North Tower, World Finance Centre,
Harbour City, Canton Road, Tsim Sha Tsui
Kowloon, Hong Kong
Tel: <852> (2) 735 9218
Fax: <852> (2) 730 0281
Telex: 40815 HITEC HX

